Applicants respectfully request reconsideration of the application, as amended, in

view of the following remarks.

The present invention as set forth in Claim 1 relates to a thermoplastic resin

composition, comprising:

a polyamide resin component comprising

(A) 5 to 95% by weight of a polyamide resin obtained by polycondensing

diamine(s) including at least tetramethylenediamine with dicarboxylic acid(s)

including at least adipic acid, based on a total amount of (A) and (B); and

(B) 95 to 5% by weight of a polyamide resin obtained by polycondensing

diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-

octanediamine with dicarboxylic acid(s) including at least terephthalic acid,

based on a total amount of (A) and (B).

In contrast, Yamagishi et al fail to disclose or suggest the specific combination of (A)

5 to 95% by weight of a polyamide resin obtained by polycondensing at least

tetramethylenediamine and at least adipic acid; and (B) 95 to 5% by weight of a

polyamide resin obtained by polycondensing at least one of 1,9-nonanediamine and 2-

methyl-1,8-octanediamine and at least terephthalic acid, as claimed in Claim 1.

In addition, as discussed on January 7, 2004, the superior properties of the claimed

composition are illustrated by the results in Table 3, second part, at page 34 of the

specification, copy of which is provided below.

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Table 3 (Second Part)

	Г		\neg	Τ	T		$\overline{}$	1	$\overline{}$		T."	_	T
n Result	Friction Property	mm³/N•km	15x10 ⁻³	15x10 ⁻³	15x10 ⁻³	16x10 ⁻³	15x10 ⁻³	15x10 ⁻³	5x10 ⁻³	15x10 ⁻³	37x10 ⁻³	5x10 ⁻³	10×10 ⁻³
	Moldability		A	A	A	A	A	A	A	A	В	A	В
	Blister Resistance [pieces]		0	0	0	0	0	0	0	10	0	S	0
Evaluation Result		Tensile Elongation [%]	2.8	2.8	2.8	2.9	2.8	2.8	30	2.8	1.2	30	14
	Mechanical Strength	Weld Strength [%]	85	80	85	85	85	85	92	85	45	92	09
		Modulus in Flexure [MPa]	13,200	13,300	13,100	12,800	13,200	13,200	3,300	12,000	12,700	3,100	3,200
			-	2	3	4	2	9	7	-	2	3	4
	Example						-	Comparative Example					

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Examples 1-7 are according to the present invention. Comparative Examples 1 and 3 are representative for data pertaining to nylon 4,6 (A), and Comparative Examples 2 and 4

pertain to the semi aromatic polyamide (B).

In the attached illustration, the upper part relates to Comparative Examples 3 and 4

and Example 7, the lower part relates to Comparative Examples 1 and 2, and Examples 1-6.

Superior results are obtained for the compositions according to the present invention

for both blistering and molding behavior. The levels of these properties are higher than could

be expected based on the weighted averages for the properties of the individual polyamides or

compositions thereof as according to Comparative Examples. (See Table 3, second part as

reproduced above and the attached illustration of the data).

In addition, the flexural modulus of the composition according to the invention is

higher than the value calculated from the blending ratio of the polyamide (A) to the

polyamide (B), whereas the friction coefficient becomes lower than the value calculated from

the blending ratio of the polyamide (A) to the polyamide (B).

Compare in this respect Example 1-6 with Comparative Examples 1 and 4 (filled

compositions), and Example 7 with Comparative Examples 3 and 4 (unfilled compositions).

Moreover, weld strength and tensile elongation remain at the good level of

polyamide-4,6 without any significant reduction due to the presence of polyamide (B).

Examples 1-7 have a good property level for all three aspects considered (blister

resistance, moldability and friction resistance), whereas all four Comparative Examples have

at least one such property which is insufficient. These results already show clearly the

surprising effect that the claimed compositions have good properties in all three aspects, and

not a mere average of the properties of the more extreme compositions. (See Table 3, second

part as reproduced above and the attached illustration of the data).

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The above results are not disclosed or suggested by Yamagishi et al.

Therefore, the rejection of Claims 1-17 and 19-20 under 35 U.S.C. § 103(a) over Yamagishi et al is believed to be unsustainable as the present invention is neither anticipated nor obvious and withdrawal of this rejection is respectfully requested.

The rejection of Claims 8-12, 14-16 and 19 under 35 U.S.C. § 112, 2nd paragraph, is obviated by the amendment of Claims 9, 11, 15 and 16.

In regard to Claim 8, Applicants note that it depends on Claim 1. The polyamide resin of component (A) is obtained by polycondensing **diamine(s)** including at least tetramethylenediamine. Thus, Claim 8 defines the diamines that may be present in addition to tetramethylenediamine.

In regard to Claims 10 and 12, Applicants note that they depend on Claim 1. The polyamide resin of component (A) is obtained by polycondensing dicarboxylic acid(s) including at least adipic acid. Thus, Claims 10 and 12 define the dicarboxylic acid that may be present in addition to adipic acid.

In regard to Claim 14, Applicants note that it depends on Claim 1. The polyamide resin of component (B) is obtained by polycondensing diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine. Thus, Claim 14 defines the diamines that may be present in addition to at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine.

Therefore the rejections of Claims 8, 10, 12 and 14 as being indefinite should be withdrawn.

With respect to withdrawn Claim 18, Applicants note that it depends from Claim 1.

Thus, if Claim 1 is allowable, Claim 18 should be allowable as well.

Applicants respectfully request that the Examiner acknowledge that the references cited in the Information Disclosure Statement, filed in the above-identified application on

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March 26, 2003, have been considered. For the Examiner's convenience a copy of Form PTO 1449 as filed on March 26, 2003, is attached herewith.

This application presents allowable subject matter, and the Examiner is kindly requested to pass it to issue. Should the Examiner have any questions regarding the claims or otherwise wish to discuss this case, he is kindly invited to contact Applicants' below-signed representative, who would be happy to provide any assistance deemed necessary in speeding this application to allowance.

Respectfully submitted,

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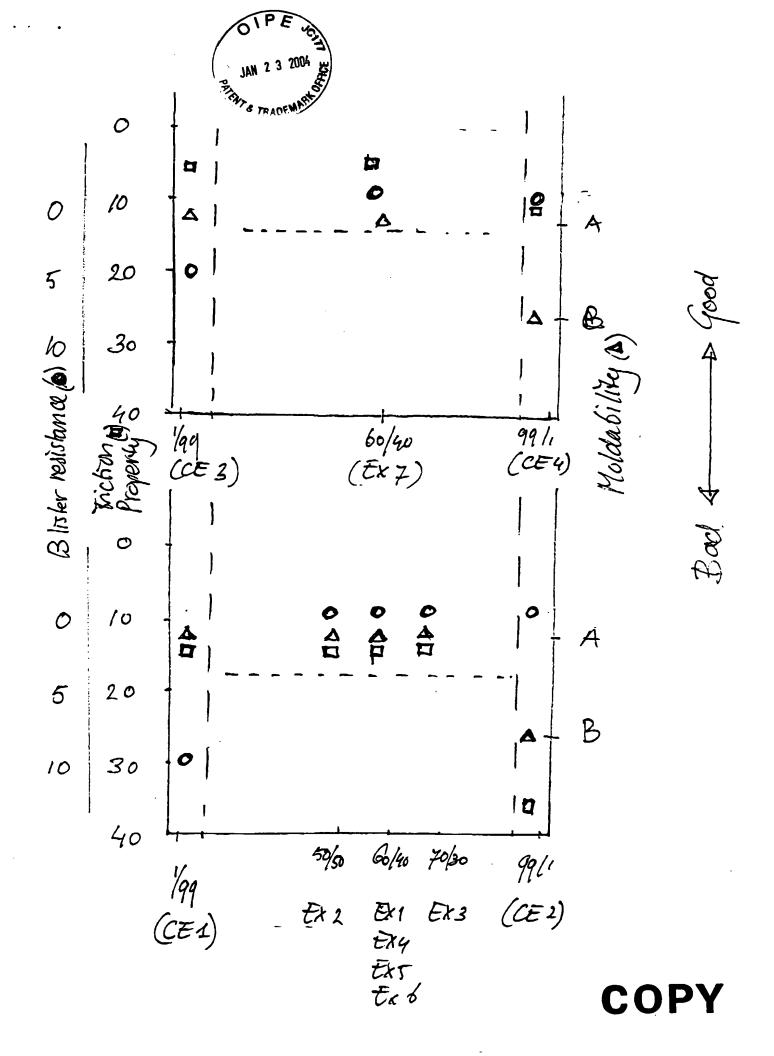
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Norman F. Oblon

Attorney of Record

Registration No.: 24,618

Kirsten A. Grueneberg, Ph.D. Registration No.: 47,297



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